



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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DA3X108K0L

Silicon epitaxial planar type

For small current rectification
 DA2J108 in Mini3 type package

■ Features

- Small reverse current IR
- High reverse voltage VR
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: 26

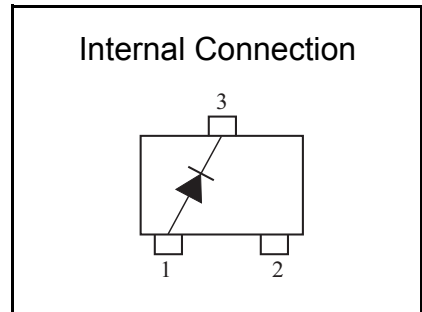
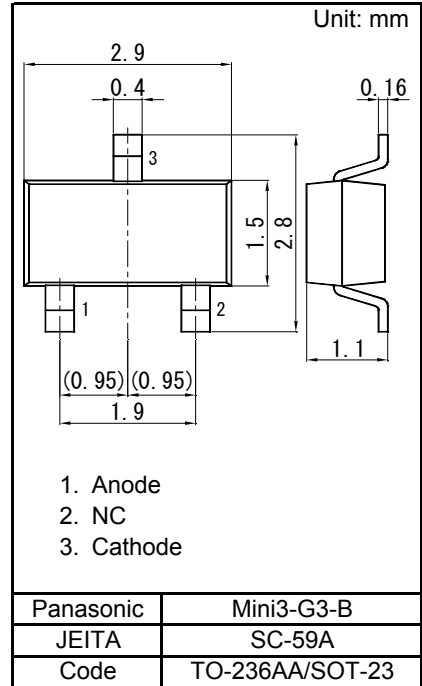
■ Packaging

Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Reverse voltage	VR	300	V
Maximum peak reverse voltage	VRM	300	V
Output current (Average)	IO (AV)	200	mA
Repetitive peak forward current	IFRM	225	mA
Non-repetitive peak forward surge current *1	IFSM	500	mA
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

Note) *1: t = 1 s



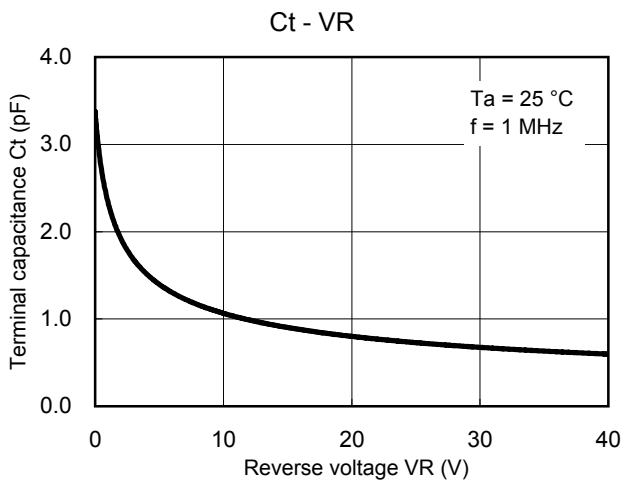
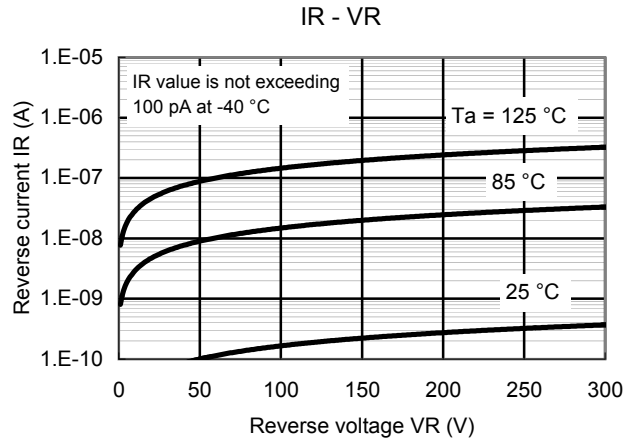
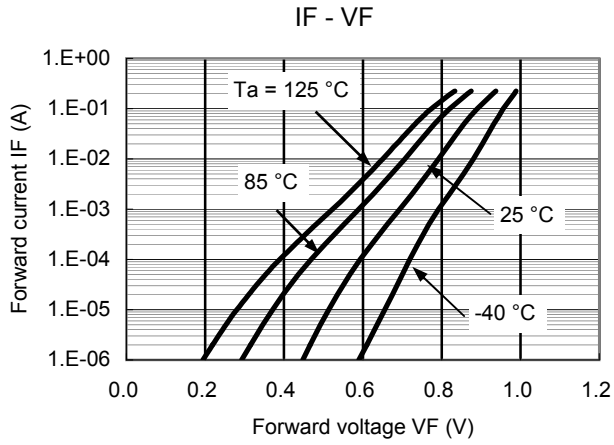


■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	VF	IF = 200 mA			1.2	V
Reverse current	IR1	VR = 200 V			200	nA
	IR2	VR = 300 V			1	μA
Terminal capacitance	Ct	VR = 0 V, f = 1 MHz		3.5		pF

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.
2. Absolute frequency of input and output is 3 MHz.

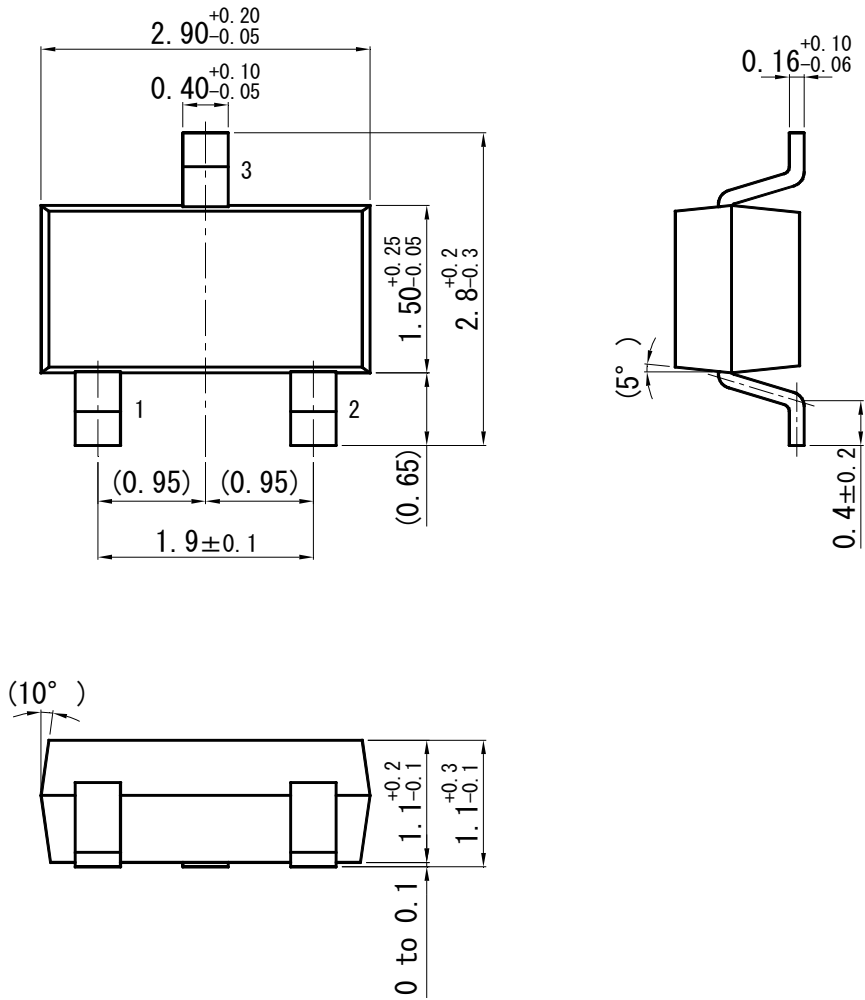
Technical Data (reference)



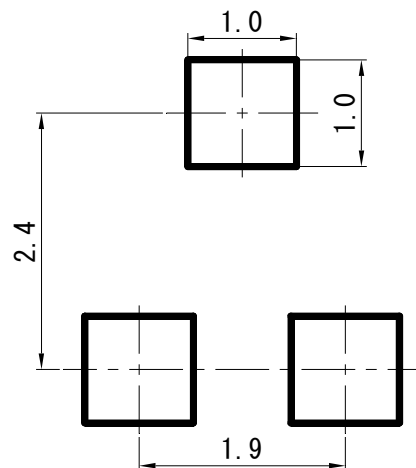


Mini3-G3-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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